


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	High-Density connection between multiple circuit boards						
Application Number: 10/813945							
Confirmation Number: 5777							
First Named Applicant: Douglas Wildes							
Attorney Docket Number: 134730							
Search string: (6520789 or 6437557 or 6309223 or 6162065 or 5871362 or 5378161).pn.							
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
<input checked="" type="checkbox"/>	1	6520789	2003-02-18	Daughert, Jr. et al.		439	329
<input type="checkbox"/>	2	6437557	2002-08-20	Smith		324	158.1
<input type="checkbox"/>	3	6309223	2001-10-30	Wolfe		439	67
<input type="checkbox"/>	4	6162065	2000-12-19	Benham		439	67
<input type="checkbox"/>	5	5871362	1999-02-16	Campbell et al.		439	67
<input checked="" type="checkbox"/>	6	5378161	1995-01-03	Loder		439	77
Signature							
Examiner Name				Date			
Michael C. Canale				4/7/05			